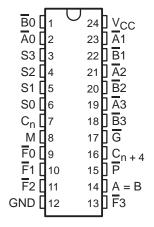
- Full Look Ahead for High-Speed Operations on Long Words
- Arithmetic Operating Modes:
 - Addition
 - Subtraction
 - Shift Operand A One Position
 - Magnitude Comparison
 - Twelve Other Arithmetic Operations
- Logic Function Modes:
 - Exclusive-OR
 - Comparator
 - AND, NAND, OR, NOR
- Package Options Include Plastic Small-Outline (N) Packages, Ceramic (FK) Chip Carriers, Standard Plastic (NT) and Ceramic (JT) 300-mil DIPs, and Ceramic (JW) 600-mil DIPs

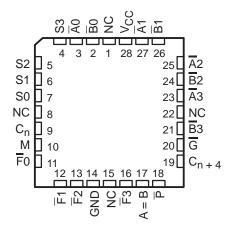
description

The SN54AS181B and SN74AS181A arithmetic logic units (ALUs)/function generators have a complexity of 75 equivalent gates on a monolithic chip. These circuits perform 16 binary arithmetic operations on two 4-bit words as shown in Tables 1 and 2. These operations are selected by the four function-select (S0, S1, S2, and S3) lines and include addition, subtraction, decrement, and straight transfer. When performing arithmetic manipulations, the internal carries are enabled by applying a low-level voltage to the mode-control (M) input. A full carry look-ahead scheme is used to generate fast, simultaneous carry by means of two cascade (\overline{G} and \overline{P}) outputs for the four bits in the package.

SN54AS181B . . . JT OR JW PACKAGE SN74AS181A . . . N OR NT PACKAGE (TOP VIEW)



SN54AS181B . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

If high speed is not important, a ripple-carry (C_n) input and a ripple-carry (C_{n+4}) output are available. The ripple-carry delay is minimized so that arithmetic manipulations for small word lengths can be performed without external circuitry.

The SN54AS181B and SN74AS181A accommodate active-high or active-low data if the pin designations are interpreted as follows:

PIN NUMBER	2	1	23	22	21	20	19	18	9	10	11	13	7	16	15	17
Active-low data (Table 1)	Ā0	B0	A 1	B1	A2	B2	A3	В3	F0	F1	F2	F3	Cn	C _{n + 4}	Р	G
Active-high data (Table 2)	A0	В0	A1	B1	A2	B2	АЗ	В3	F0	F1	F2	F3	\overline{C}_n	\overline{C}_{n+4}	X	Υ

Subtraction is accomplished by 1's complement addition where the 1's complement of the subtrahend is generated internally. The resultant output is A-B-1, which requires an end-around or forced carry to provide A-B.



description (continued)

The SN54AS181B and SN74AS181A also can be used as comparators. The A = B output is internally decoded from the function (F0, F1, F2, F3) outputs so that when two words of equal magnitude are applied at the A and B inputs, the output assumes a high level to indicate equality (A = B). The ALU must be in the subtract mode with C_n = H when performing this comparison. The A = B output is open collector so that it can be wire-AND connected to give a comparison for more than four bits. C_{n+4} also can be used to supply relative magnitude information. The ALU must be placed in the subtract mode by placing the function-select inputs S3, S2, S1, and S0 at L, H, H, and L, respectively.

INPUT C _n	OUTPUT C _{n + 4}	ACTIVE-LOW DATA (Figure 1)	ACTIVE-HIGH DATA (Figure 2)
Н	Н	A≥B	$A \leq B$
Н	L	A < B	A > B
L	Н	A > B	A < B
L	L	$A \leq B$	$A \ge B$

These circuits not only incorporate all of the designer's requirements for arithmetic operations, but also provide 16 possible functions of two Boolean variables without using external circuitry. These logic functions are selected by the four function-select inputs with M at a high level to disable the internal carry. The 16 logic functions are detailed in Tables 1 and 2 and include exclusive-OR, NAND, AND, NOR, and OR functions.

TYPICAL ADDITION TIME (CL = 15 pF, RL = 280 Ω , TA = 25°C)

	ADDITION	PACK	AGE COUNT			
NUMBER OF BITS	TIME USING 'S181 AND 'S182	ALUs	LOOK-AHEAD CARRY GENERATORS	CARRY METHOD BETWEEN ALUS		
1 to 4	11 ns	1		None		
5 to 8	18 ns	2		Ripple		
9 to 16	19 ns	3 or 4	1	Full look ahead		
17 to 64	28 ns	5 to 16	2 to 5	Full look ahead		

The SN54AS181B is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74AS181A is characterized for operation from 0°C to 70°C.

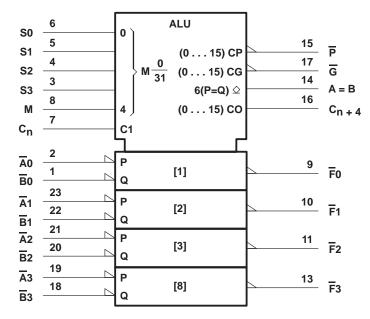
application note

An application-specific problem has been identified in the SN54AS181B device. The F0–F4 outputs exhibit voltage transients when one or more B-data inputs transition from a high to a low state. The resultant voltage transients can have an amplitude of 2 V relative to V_{OL} with a width of 5 ns at an input threshold of 1.5 V. The transient pulse occurs coincidentally with the high-to-low transition of the B-data input(s) and appears to be caused by internal coupling.

In system operations in which this device is used, it is likely that transmission-line effects minimize this anomaly. Narrow width of the voltage transient makes the pulse transparent to most circuitry; however, in certain applications, the transients can cause system errors.



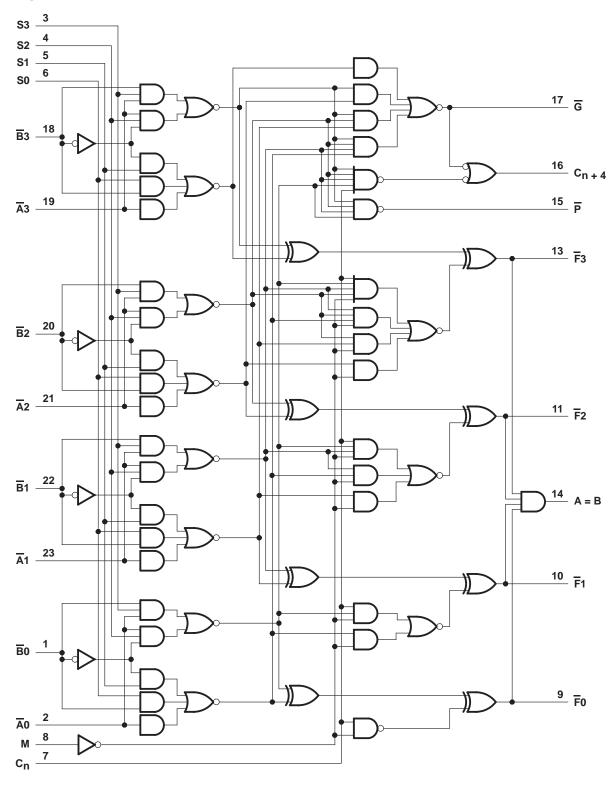
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the JT, JW, N, and NT packages.



logic diagram



Pin numbers shown are for the JT, JW, N, and NT packages.



signal designations

In Figures 1 and 2, the polarity indicators (□) indicate that the associated input or output is active low with respect to the function shown inside the symbol. The symbols are the same in both figures. The signal designations in Figure 1 agree with the indicated internal functions based on active-low data and are for use with the logic functions and arithmetic operations shown in Table 1. The signal designations have been changed in Figure 2 to accommodate the logic functions and arithmetic operations for the active-high data given in Table 2. The SN54AS181B and SN74AS181A together with the 'S182 can be used with the signal designation of either Figure 1 or Figure 2.

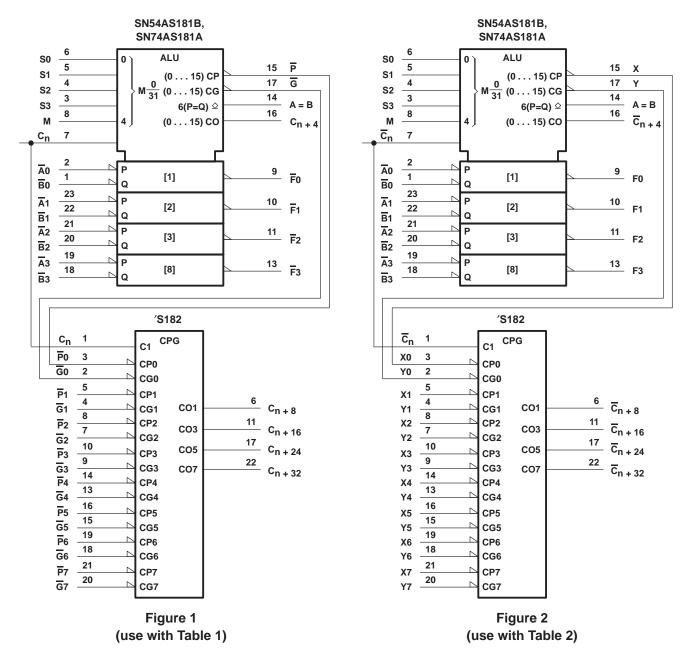


Table 1

	SEL E	CTION			ACTIVE-LOW DA	CTIVE-LOW DATA				
	SELE	CHON		M = H	M = L; ARITHME	ETIC OPERATIONS				
S3	S2	S 1	S0	LOGIC FUNCTIONS	C _n = L (no carry)	C _n = H (with carry)				
L	L	L	L	$F = \overline{A}$	F = A MINUS 1	F = A				
L	L	L	Н	$F = \overline{AB}$	F = AB MINUS 1	F = AB				
L	L	Н	L	$F = \overline{A} + B$	$F = A\overline{B}$ MINUS 1	$F = A\overline{B}$				
L	L	Н	Н	F = 1	F = MINUS 1 (2's COMP)	F = ZERO				
L	Н	L	L	$F = \overline{A + B}$	$F = A PLUS (A + \overline{B})$	$F = A PLUS (A + \overline{B}) PLUS 1$				
L	Н	L	Н	$F = \overline{B}$	$F = AB PLUS (A + \overline{B})$	$F = AB PLUS (A + \overline{B}) PLUS 1$				
L	Н	Н	L	$F = \overline{A \oplus B}$	F = A MINUS B MINUS 1	F = A MINUS B				
L	Н	Н	Н	$F = A + \overline{B}$	$F = A + \overline{B}$	$F = (A + \overline{B}) PLUS 1$				
Н	L	L	L	$F = \overline{A}B$	F = A PLUS (A + B)	F = A PLUS (A + B) PLUS 1				
Н	L	L	Н	$F = A \oplus B$	F = A PLUS B	F = A PLUS B PLUS 1				
Н	L	Н	L	F = B	$F = A\overline{B} PLUS (A + B)$	$F = A\overline{B} PLUS (A + B) PLUS 1$				
Н	L	Н	Н	F = A + B	F = (A + B)	F = (A + B) PLUS 1				
Н	Н	L	L	F = 0	F = A PLUS A [†]	F = A PLUS A PLUS 1				
Н	Н	L	Н	$F = A\overline{B}$	F = AB PLUS A	F = AB PLUS A PLUS 1				
Н	Н	Н	L	F = AB	$F = A\overline{B} PLUS A$	F =AB PLUS A PLUS 1				
Н	Н	Н	Н	F = A	F = A PLUS 1	F = A PLUS 1				

[†] Each bit is shifted to the next more significant position.

Table 2

	SELE	CTION			ACTIVE-HIGH DATA						
	SELE	CHON		M = H	M = L; ARITHMETIC OPERATIONS						
S3	S2	S1	S0	LOGIC FUNCTIONS	C _n = H (no carry)	C _n = L (with carry)					
L	L	L	L	$F = \overline{A}$	F = A	F = A PLUS 1					
L	L	L	Н	$F = \overline{A + B}$	F = A + B	F = (A+ B) PLUS 1					
L	L	Н	L	$F = \overline{A}B$	$F = A + \overline{B}$	$F = (A + \overline{B}) PLUS 1$					
L	L	Н	Н	F = 0	F = MINUS 1 (2's COMPL)	F = ZERO					
L	Н	L	L	$F = \overline{AB}$	F = A PLUS AB	F = A PLUS AB PLUS 1					
L	Н	L	Н	$F = \overline{B}$	F = (A + B) PLUS AB	F =(A + B) PLUS AB PLUS 1					
L	Н	Н	L	$F = A \oplus B$	F = A MINUS B MINUS 1	F = A MINUS B					
L	Н	Н	Н	$F = A\overline{B}$	$F = A\overline{B}$ MINUS 1	$F = A \overline{B}$					
Н	L	L	L	$F = \overline{A} + B$	F = A PLUS AB	F = A PLUS AB PLUS 1					
Н	L	L	Н	$F = \overline{A \oplus B}$	F = A PLUS B	F = A PLUS B PLUS 1					
Н	L	Н	L	F = B	$F = (A + \overline{B}) PLUS AB$	$F = (A + \overline{B})$ PLUS AB PLUS 1					
Н	L	Н	Н	F = AB	F = AB MINUS 1	F = AB					
Н	Н	L	L	F = 1	F = A PLUS A [†]	F = A PLUS A PLUS 1					
Н	Н	L	Н	$F = A + \overline{B}$	F = (A + B) PLUS A	F = (A + B) PLUS A PLUS 1					
Н	Н	Н	L	F = A + B	$F = (A + \overline{B}) PLUS A$	$F = (A + \overline{B}) PLUS A PLUS 1$					
Н	Н	Н	Н	F = A	F = A MINUS 1	F = A					

[†] Each bit is shifted to the next more significant position.



SN54AS181B, SN74AS181A ARITHMETIC LOGIC UNITS/FUNCTION GENERATORS

SDAS209B - DECEMBER 1982 - REVISED DECEMBER 1994

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 \
Input voltage, V _I	
Off-state output voltage (A = B output only)	7 \
Operating free-air temperature range, T _A : SN54AS181B	-55°C to 125°C
SN74AS181A	0°C to 70°C
Storage temperature range	-65°C to 150°C

recommended operating conditions

			SN	54AS18	1B	SN	74AS18′	1A	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
٧ _{IH}	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage				0.8			0.8	V
Vон	High-level output voltage	A = B output only			5.5			5.5	V
1	Link lovel output ourrent	All outputs except A = B and \overline{G}			-2			-2	A
ЮН	High-level output current	G			-3			-3	mA
la.	Low lovel output ourrent	All outputs except G			20			20	A
IOL	Low-level output current	G			48			48	mA
TA	Operating free-air temperature		-55		125	0		70	°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

SN54AS181B, SN74AS181A ARITHMETIC LOGIC UNITS/FUNCTION GENERATORS

SDAS209B - DECEMBER 1982 - REVISED DECEMBER 1994

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST CONF	NTIONS	SN	54AS18	1B	SN	74AS18	1A	UNIT
	PARAMETER	TEST CONE	DITIONS	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNII
VIK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
V	Any output except A = B	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		V
VOH	G	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.4	3.4		2.4	3.4		V
Val	Any output except G	V00 - 45 V	I _{OL} = 20 mA		0.3	0.5		0.3	0.5	V
VOL	G	VCC = 4.5 V	I _{OL} = 48 mA		0.4	0.5		0.4	0.5	V
IOH	A = B	$V_{CC} = 4.5 \text{ V},$	V _{OH} = 5.5 V			0.1			0.1	mA
	М					0.1			0.1	
ļ.,	Any A or B	V _{CC} = 5.5 V,	\/ı = 7 \/			0.3			0.3	mA
11	Any S	vCC = 5.5 v,	V = I V			0.4			0.4	IIIA
	C _n					0.6			0.6	
	М					20			20	
l	Any A or B	V _{CC} = 5.5 V,	\/ 2.7.\/			60			60	
IН	Any S	vCC = 5.5 v,	V = 2.7 V			80			80	μΑ
	C _n					120			120	
	М					-0.5			-2	
1	Any A or B	\/	\/. 0.4\/			-1.5			-6	A
ll L	Any S	V _{CC} = 5.5 V,	V = 0.4 V			-2			-8	mA
	C _n					-3			-12	
1 ₀ ‡	All outputs except $A = B$ and \overline{G}	V _{CC} = 5.5 V,	V _O = 2.25 V	-30	-45	-112	-30	-45	-112	mA
	G			-30		-125	-30		-125	
ICC		V _{CC} = 5.5 V			74	117		135	200	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS [†]	V _C C _L R _L T _A SN54A	V, S181A	UNIT			
				MIN	MAX	MIN	MAX		
^t PLH	C _n			3	9	2	9	ns	
^t PHL	∨n	C _{n + 4}		2	7	2	9	113	
t _{PLH}	Any \overline{A} or \overline{B}	C _{n + 4}	M = 0, $S1 = S2 = 0$, $S0 = S3 = 4.5 V (SUM mode)$	2	16 14	2	12 12	ns	
tPHL			<u> </u>	3	18	4	16		
tPLH tPHL	Any \overline{A} or \overline{B}	C _{n + 4}	M = 0, $S1 = S3 = 0$, S1 = S2 = 4.5 V (DIFF mode)	3	14.5	2	16	ns	
t _{PLH}			,	3	10.5	3	9		
t _{PHL}	C _n	Any F	M = 0 (SUM or DIFF mode)	3	10	3	9	ns	
t _{PLH}		_	M = 0, $S1 = S2 = 0$,	3	9.5	2	8		
t _{PHL}	Any \overline{A} or \overline{B}	G	S0 = S3 = 4.5 V (SUM mode)	2	7	2	7	ns	
t _{PLH}	A	G	M = 0, $S1 = S3 = 0$,	3	12	2	9.5	20	
^t PHL	Any \overline{A} or \overline{B}	G	S1 = S2 = 4.5 V (DIFF mode)	2	9	2	9	ns	
^t PLH	Any A or B	P	M = 0, $S1 = S2 = 0$,	3	9.5	2	8	ns	
^t PHL	Ally A of B	-	S0 = S3 = 4.5 V (SUM mode)	2	7.5	2	8	110	
^t PLH	Any $\overline{\overline{A}}$ or $\overline{\overline{B}}$	P	M = 0, $S1 = S3 = 0$,	3	12	2	10	ns	
^t PHL	7 , 7		S1 = S2 = 4.5 V (DIFF mode)	3	8.5	2	10		
tPLH	Ai or Bi	Fi	M = 0, $S1 = S2 = 0$,	3	11	2	9.5	ns	
tPHL			S0 = S3 = 4.5 V (SUM mode)	3	9	2	8		
tPLH	Ai or Bi	Fi	M = 0, $S1 = S3 = 0$, $S1 = S2 = 4.5 V (DIFF mode)$	3	13.5 11	2	10.5	ns	
tPHL			01 - 02 - 4.0 V (Dil 1 Illode)	3	11	2	10		
tPLH	Ai or Bi	Fi	M = 4.5 V (LOGIC mode)	3	10	2	11	ns	
t _{PHL}			M = 0, S1 = S3 = 0,	2	19	4	21		
tPHL	Any \overline{A} or \overline{B}	A = B	S1 = S2 = 4.5 V (DIFF mode)	3	22	4	21	ns	

[†] Refer to the parameter measurement information tables for the SUM-, DIFF-, and LOGIC-mode test tables.

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION

SUM-MODE TEST TABLE (Function Inputs: S0 = S3 = 4.5 V, S1 = S2 = M = 0)

PARAMETER	INPUT UNDER		R INPUT IE BIT	OTHER DA	ATA INPUTS	OUTPUT UNDER	OUTPUT WAVEFORM	
PARAMETER	TEST	APPLY APPLY 4.5 V GND		APPLY 4.5 V	APPLY GND	TEST	(See Note 1)	
tPLH tPHL	Āi	Bi	None	Remaining A and B	Cn	- Fi	In phase	
t _{PLH}	Bi	Āi	None	Remaining A and B	Cn	Fi	In phase	
t _{PLH}		Bi	None	None	Remaining A and B, C _n	P	In phase	
tPLH tPHL	Bi	Āi	None	None	Remaining A and B, C _n	P	In phase	
tPLH tPHL	- Ai	None	Bi	Rem <u>ai</u> ning B	Remaining Ā, C _n	G	In phase	
^t PLH ^t PHL	Bi	None	Āi	Remaining B	Remaining Ā, C _n	G	In phase	
^t PLH ^t PHL	Cn	None	None	All Ā	All B	Any F or C _{n + 4}	In phase	
tPLH tPHL	Āi	None	_ Bi	Remaining B	Remaining Ā, C _n	C _{n + 4}	Out of phase	
[†] PLH [†] PHL	Bi	None	Āi	Remaining B	Remaining Ā, C _n	C _{n + 4}	Out of phase	

PARAMETER MEASUREMENT INFORMATION

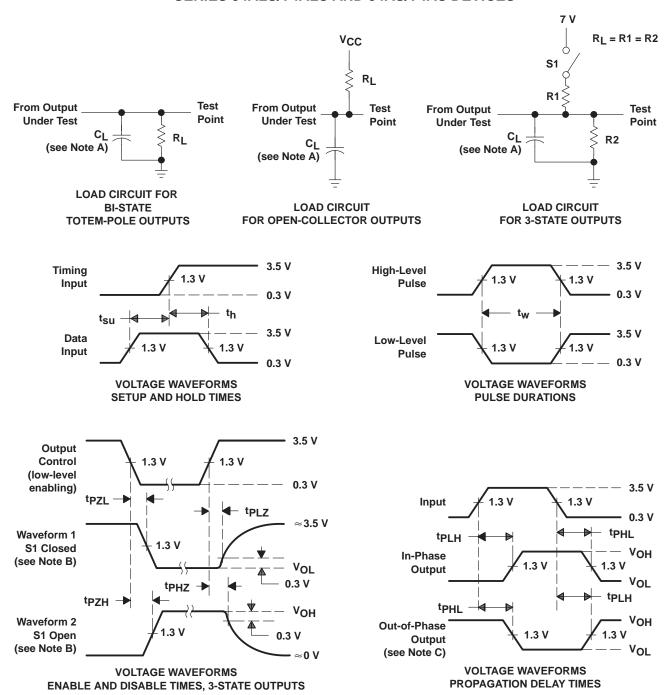
PARAMETER	INPUT	OTHER SAME	_	OTHER DA	ATA INPUTS	OUTPUT	OUTPUT
PARAMETER	UNDER TEST	APPLY 4.5 V	APPLY GND	APPLY 4.5 V	APPLY GND	UNDER TEST	WAVEFORM (See Note 1)
tPLH	_ Ai	None	 Bi	Rem <u>a</u> ining	Remaining	Fi	In phase
t _{PHL}	7.1	140110	٥,	А	B, C _n		III pridoc
t _{PLH}	Bi	Āi	None	Rem <u>ai</u> ning Ā	Remaining B, C _n	Fi	Out of phase
tPLH tPHL	Āi	None	Bi	None	Remaining A and B, C _n	P	In phase
tPLH tPHL	 Bi	Āi	None	None	Remaining A and B, C _n	P	Out of phase
tPLH tPHL	Āi	- Bi	None	None	Remaining A and B, C _n	G	In phase
t _{PLH}	Bi	None	Āi	None	Remaining A and B, C _n	G	Out of phase
[†] PLH [†] PHL	Āi	None	Bi	Remaining Ā	Remaining B, C _n	A = B	In phase
t _{PLH}	Bi	Āi	None	Rem <u>ai</u> ning Ā	Remaining B, C _n	A = B	Out of phase
t _{PLH}	Cn	None	None	All All A and B	None	C _{n + 4} or any F	In phase
t _{PLH}	Āi	Bi	None	None	Remaining Ā, B, C _n	C _{n + 4}	Out of phase
tPLH tPHL	Bi	None	Āi	None	Remaining A, B, C _n	C _{n + 4}	In phase

LOGIC-MODE TEST TABLE

(Function Inputs: S1 = S2 = M = 4.5 V, S0 = S3 = 0)

PARAMETER	INPUT UNDER	OTHER INPUT SAME BIT		OTHER DA	ATA INPUTS	OUTPUT UNDER	OUTPUT WAVEFORM
PARAMETER	TEST	I ADDIV I ADDIV I ADDIV			TEST	(See Note 1)	
^t PLH	- Ai	— Bi	None	None	Remaining	- Fi	Out of phase
^t PHL	Al	ы	None	None	\overline{A} and \overline{B} , C_n	Г	Out of priase
t _{PLH}	— Bi	— Ai	None	None	Remaining	Fi	Out of phase
t _{PHL}	ы	Al	None	None	\overline{A} and \overline{B} , C_n	П	Out of priase

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- The outputs are measured one at a time with one transition per measurement.

Figure 3. Load Circuits and Voltage Waveforms



PACKAGE OPTION ADDENDUM

www.ti.com 27-Aug-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN54AS181BJT	OBSOLETE	CDIP	JT	24	TBD	Call TI	Call TI
SN74AS181ADWE4	ACTIVE	SOIC	DW	24	TBD	Call TI	Call TI
SN74AS181ADWG4	ACTIVE	SOIC	DW	24	TBD	Call TI	Call TI
SN74AS181ADWRE4	ACTIVE	SOIC	DW	24	TBD	Call TI	Call TI
SN74AS181ADWRG4	ACTIVE	SOIC	DW	24	TBD	Call TI	Call TI
SN74AS181AN	OBSOLETE	PDIP	N	24	TBD	Call TI	Call TI
SN74AS181ANTE4	ACTIVE	PDIP	NT	24	TBD	Call TI	Call TI
SNJ54AS181BFK	OBSOLETE	LCCC	FK	28	TBD	Call TI	Call TI
SNJ54AS181BJT	OBSOLETE	CDIP	JT	24	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

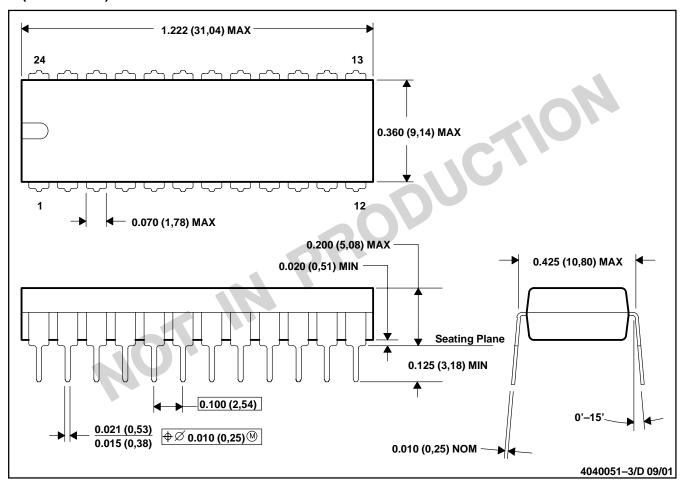
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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N (R-PDIP-T24)

PLASTIC DUAL-IN-LINE

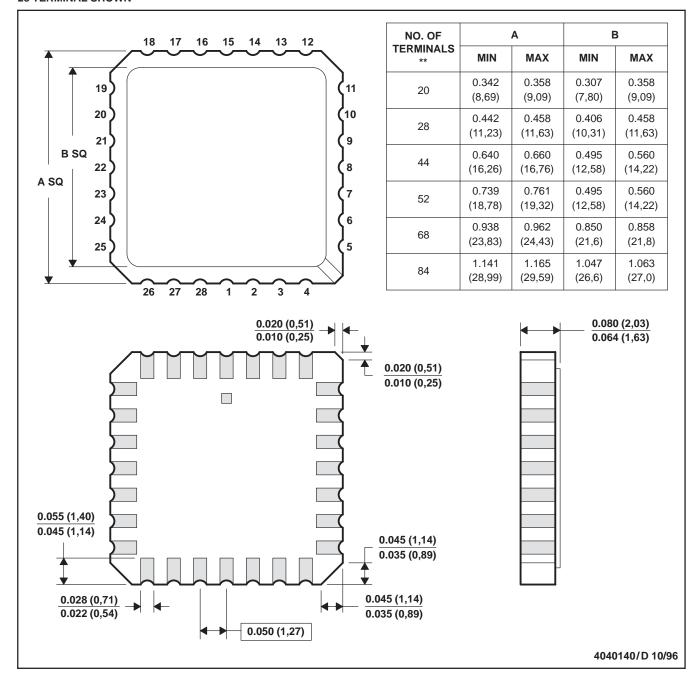


- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-010

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



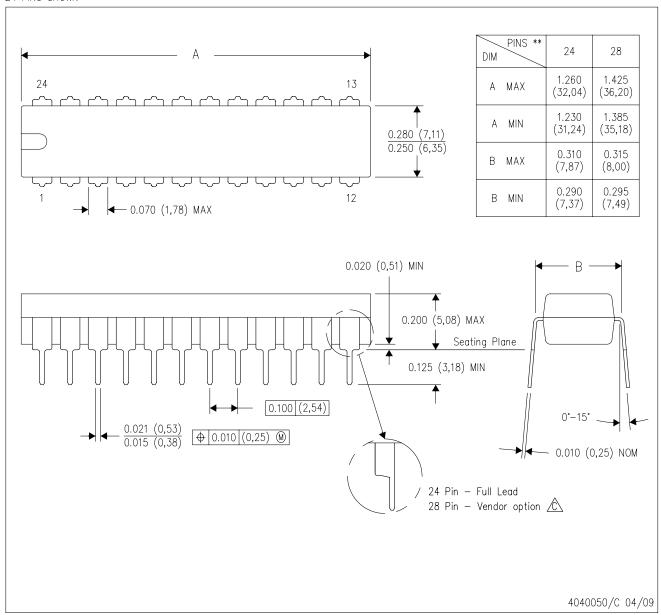
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

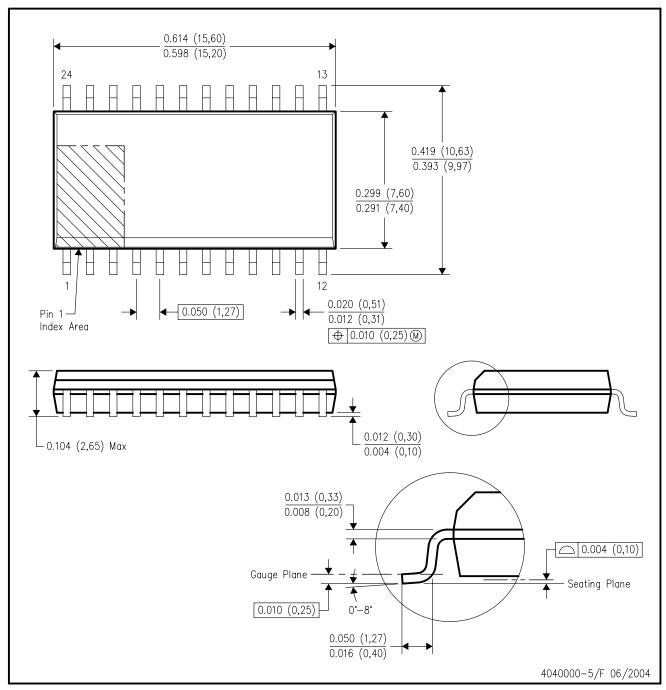
B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

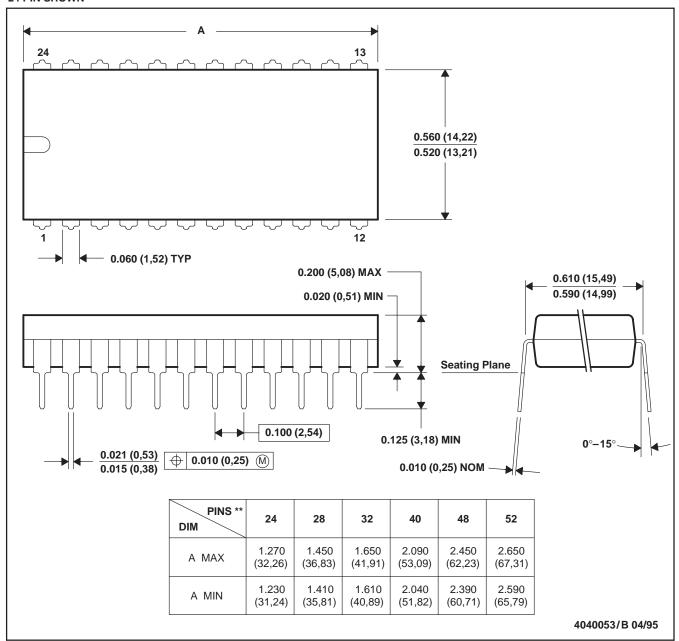
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PIN SHOWN



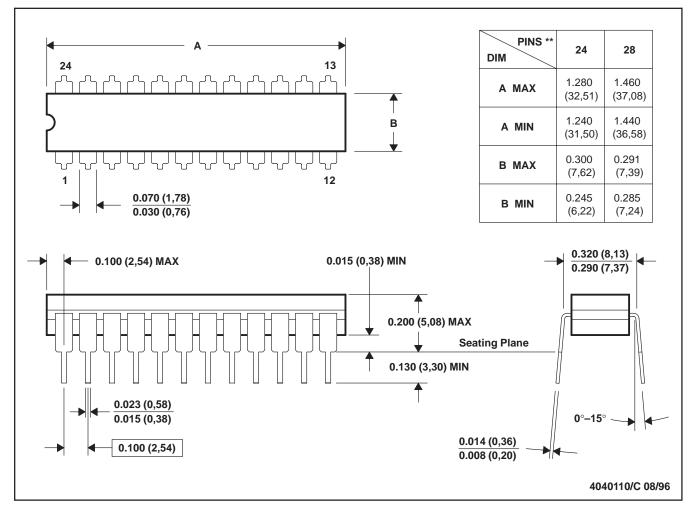
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-011
- D. Falls within JEDEC MS-015 (32 pin only)



JT (R-GDIP-T**)

24 LEADS SHOWN

CERAMIC DUAL-IN-LINE



- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

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